

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. **Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date.** ADI contact information is listed below.

PCN Title:	Wafer size change (6-to-8 inch) for ADI products in S3 process (from S3K to B3K)
Publication Date:	02-Jun-2023
Effectivity Date:	04-Sep-2023 (the earliest date that a customer could expect to receive changed material)
Revision Description:	

Description Of Change:

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Wafer size change for ADI products in current S3 process
Current 6-inch wafer size fabricated at ADI's Beaverton/Oregon foundry (ADBN)

Reason For Change:

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ADI is moving to the 8-inch process to ensure adequate capacity for supply continuity.
ADI has been shipping products fabricated on 8-inch wafers in mass production from ADBN since 2010.

The 8-inch flow reliability/qualification report is attached.

The Form/Fit/Function of the devices is unchanged.

Impact of the change (positive or negative) on fit, form, function & reliability:

Product Identification (this section will describe how to identify the changed material):

Summary of Supporting Information:

Supporting Documents:

ADI Contact Information:

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas:	Europe:	Japan:	Korea:	Rest of Asia:
PCN_Americas@analog.com	PCN_Europe@analog.com	PCN_Japan@analog.com	PCN_Korea@analog.com	PCN_ROA@analog.com

Appendix A - Impacted items, see csv PN listing in PCN Zip file